Technical Manual of HOB Technique



The status quo of LED package

As is known to us, LED display, in comparison to LCD and DLP screens, has much huge advantages. It is seen widely application in the current market and also in radio and television broadcasting, which is done by mainstream SMD technique. It, however, reveals certain disadvantages and causes pains.

Heavy moiré patterns on screen of digital device

Conventional LED screens, with masks or without, always are hunted by the light reflection on surface when in front of a digital camera, and it worsens displaying cold colors.

Poor protection and incurs damages to screen and its masks during transportation and installation.

Maximum viewing angle of led screen is within 145 °, giving unsatisfying viewing effects.

Particles, vapor, static electricity, moisture and other elements would make LED screen vulnerable to malfunction, such as LED failure.

Issues remained unsolved in this industry

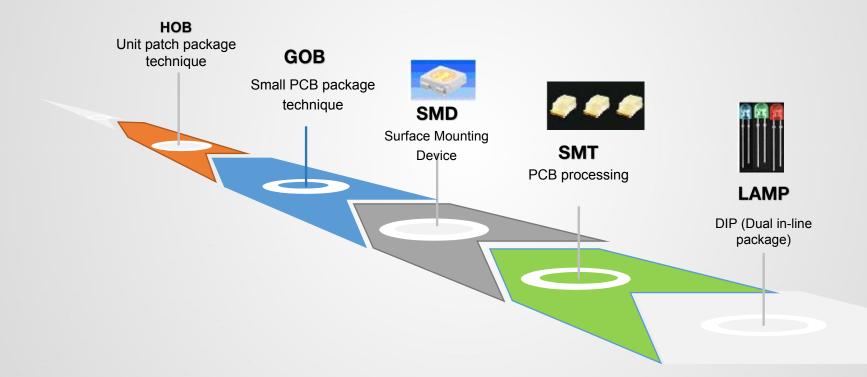
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Technical issues

- High temperature in reflow soldering unavoidably brings damage to LEDs
- Exposed directly to the air, LEDs are open to any natural risks like oxidization, moisture, static electricity, etc., which cause LED failure or malfunction
- Color variation or color cast is shown on unit patches of one module

Comprehensive Analysis of HOB

♦ High temperature gluing in all sides to cover complete protection of LED surface.

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• Epoxy resin is used to package LEDs in vacuum condition and then processed curing after compression molding method under high temperatures.

 Uniformity of thermal conductivity is an advantage to enhance thermal distribution and reduce color cast caused by temperature variation.

 Surface harness of resin higher than 70 HRC (Hardness Rockwell C) ensuring great durability.



 Heavy investment in equipment like compression molding machine.

 Modular patches on the module are frustratingly difficult to repair and maintain, which therefore are required technical operation back in manufacturing sites.

05

Refilling method on Nanoscale Photonic Thermal Conductivity Materials

Technical

The new HOB (High-temperature On Board) technique developed by our R&D team is designed for, not only enhancement of SMD LED modules, but compatible with COB led modules, which fit well and remove most of deficiencies in this industry. Its surficial layer is seamless and gives clear expression and anti-blue light, which, as a whole, relieve condition of sore eyes after long viewing the led screen.

HOB technique: HOB is an technology where epoxy resin is processed under high temperature in vacuum environment to package the LED modules for the second time and produce smooth layers photonic processing, which, as a result, improves screen performance, functional stability, prolong its life cycle, and contributes to high first pass yield.



1. Better thermal stability and adaptability to surroundings than GOB.

2. Maintenance of singular LED on the LED patch complement to the shortcoming of COB.

3. Moiré pattern reduces largely comparing with SMD technology

4. Longer life span than SMD products

5. More capable of protecting from moisture, collision, static electricity



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产品技术8大优势



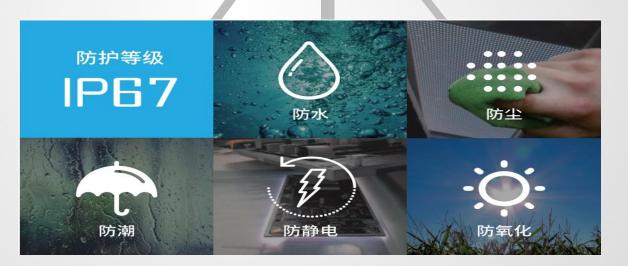
Parametric standards:

- 1. Glue hardness: over 35D
- Module surface roughness:
 0.02mm (20µ)
- 3. Brightness loss: 90%
- 4. Trimming precision: ≤0.03mm
- 5.Temperature range: -20 ° + 80 °
- 6. Glue thickness: 0.035-0.05

01. IP level

Six functions

The nanoscale photonic layer is applied on the surface seamlessly and prevent external contact, exposure of LED pins. It therefore effectively meet functions of waterproof, antidust, anti-static electricity, anti-corrosion, and anti-oxidation. The protection rating is safely rated as 67.

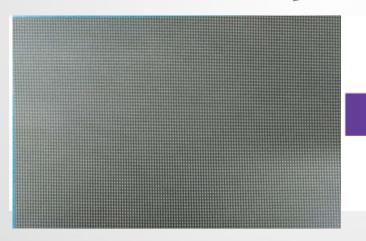


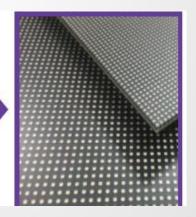


Stress like collision applied on LED module surface would cause LEDs fall off easily because SMD LEDs are soldered on the PCB but still leaves room.

> Before ready for use, much damage like sudden movement or collision during transportation or installation would increase LED failure rate, which will be a "disaster" for a project case.

Our HOB technology ensures the bond between LEDs and PCB are sealed closely enough, as safe and hardened to form a solid protection layer against collision.







Smooth surface

(expandable as interactive screen)

Surface: Smooth layer after special procedures shows great effect on surface and improved surficial ink distribution, which makes the screen look uniform in pure black color when the screen is off.



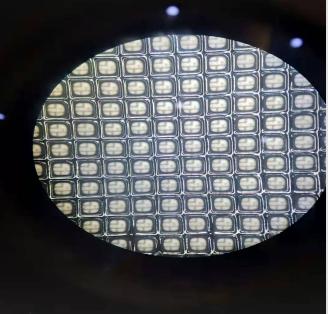




Overall thermal conductivity in the heat dissipation system of an led screen is regarded an significant indicator to its quality. But for that in traditional LED package technologies, gap exists and comes in the way between LED chips.

The LED products processed by HOB method is proved to remove gap and carry away heat between LEDs and pcb in an effective way, because the filled layer is made of nanoscale photonic thermally-conductive materials. That is, the whole LED module is considered as a flat section to transfer heat down the inside, which is constructively helpful to prolong its life span, and keep its performance.



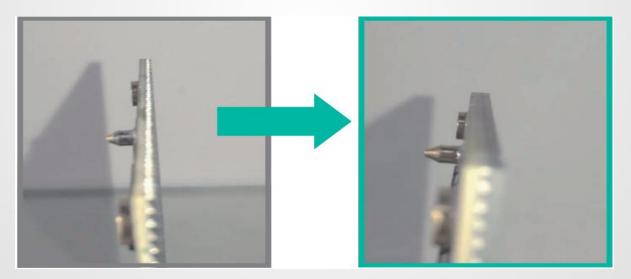




Assembly with precision

Our GOB products have smooth, crystal surface (processed by DIAO cnc machine) and undergoes high-precision trimming, which leads to its 0.02mm in surface roughness.





⁰⁶ Bright colors and softened expression

The surface layer in black matte is characteristic of reducing diffuse reflection, moire pattern; and it also raises contrast ratio, alleviates sensation of dazzle and glare, which in mass helps relieve eyes of exhaustion.



同种产品未用我司工艺单蓝色中呈现 不均匀发光现象



同批次显示产品使用我司工艺后发光 均匀,颜色更柔和。 >> Blue colors of SMD LEDs not evenly distributed on the same LED screen

>> Much improvement present in overall color uniformity on same screen but with HOB technology

>> HOB LEDs in the same batch credited with even brightness distribution and softened colors.





Features	SMD	COB	HOB
Waterproof	×		
Moisture proof	\mathbf{x}		
Anti-dust	\mathbf{x}		
Anti-static electricity	\mathbf{x}		
Anti-oxidation	8		
Anti-collision	8		
Anti-radiation			
Anti-moire	8	8	
Visual comfort	8		∎
LED Color uniformity			
Uniformity thermal			La companya da
conductivity		•.8	•.8
Interactivity	×		La
(touchscreen)	•	8	B
Maintainability	Good	Bad	Between good and bad